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| COMSOL, Inc.  1 New England Executive Park  Burlington, MA 01803 USA  Phone: +1 781-273-3322  Web: [www.comsol.com](http://www.comsol.com)  Blog: [www.comsol.com/blogs](http://www.comsol.com/blogs) | Media Contact:  Natalia Switala, PR & Communications Project Manager [natalia@comsol.com](mailto:natalia@comsol.com)  *Register for the COMSOL Conference 2015:*  [*www.comsol.com/conference2015*](http://www.comsol.com/conference2015) |

**COMSOL Announces Keynotes for Boston 2015**

**COMSOL Conference on Multiphysics Simulation**

Boston: Oct 7-9 | Grenoble: Oct 14-16 | Pune: Oct 29-30 | Beijing: Nov 4-5

Curitiba: Nov 5-6 | Kuala Lumpur: Nov 11-12 | Taipei: Nov 13 | Seoul: Nov 27 | Tokyo: Dec 3-4

BURLINGTON, MA (September 1, 2015) — COMSOL, the leading provider of multiphysics modeling and simulation software, is pleased to announce the featured customers who have been invited as keynote speakers for the [11th Annual COMSOL Conference](http://www.comsol.com/conference2015), Boston’s leading event for multiphysics simulation and application design. The 2015 Boston keynotes include:

• **Rick Beyerle**, senior research scientist in the Innovation and TechnologyGroup at GrafTech International

• **Dritan Celo,** photonic integrated circuit (PIC) designer at Huawei Canada Research Centre

• **Stuart Brown,** managing partner at Veryst Engineering



**KEYNOTE: A World of Multiphysics Applications in Carbon and Graphite**

At GrafTech, **Rick Beyerle** is responsible for the characterization and modeling of natural and synthetic graphite foils. He began his career doing simulations in the Microgravity Science Department at NASA Glenn Research Center, where he modeled the effect of orbital thermal loads on space hardware. Beyerle also designed microprocessor test equipment and telecommunications devices. He holds several patents for controlling the temperature of a microprocessor during testing and recently presented the paper “Development of Heat Transfer Tools for Sizing Flexible Graphite Spreaders in Mobile Applications" at the ASME InterPACK Conference.

**KEYNOTE: Heat Transfer Model of Ultraconnect Optical Switches on Silicon Photonics Technology**

The current research interests of **Dritan Celo** include silicon PICs, optical components, optical switches, optoelectronic packaging, electro-optic modulators, and 100 Gbps optical links. Celo has published over 40 peer-reviewed journal and conference publications. In 2009, he joined the Communications Research Center in Ottawa where he developed photonic and RF-photonic components on Silica-on-Silicon and SOI technologies. Previously, he received his Ph.D. at Carleton University and worked at the National Research Council (NRC) in Canada, where he developed silicon nitride PIC components for sensing applications.

**KEYNOTE: Forensic Engineering: Multiphysics Simulation Unravels Elevator Brake Failure.**

**Stuart Brown’s** background includes mechanical engineering and materials science. He has experience with a wide variety of materials encompassing metals, polymers, composites, and ceramics. Prior to founding engineering consulting firm Veryst Engineering, Brown was director of the Boston Office of Exponent, Inc. Before Exponent, Brown was on the faculty of the Department of Materials Science and Engineering at the Massachusetts Institute of Technology.

**2015 COMSOL Conference**

The 2015 COMSOL Conference world tour begins on October 7th in Boston. The event focuses on advancing cross-discipline and multiphysics simulation and application design through a multitude of hands-on sessions, networking opportunities, keynote talks from industry leaders, and over 700 user presentations. The Conference brings together more than 2,000 engineers, researchers, and scientists worldwide throughout nine locations, providing them with the chance to showcase their work, share innovative technologies and best practices, as well as the opportunity to interact with the developers of the COMSOL Multiphysics® software.

#### The 2015 conference will feature presentations on simulation apps using the Application Builder and the COMSOL Server™ license. Other highlights include:

* Over 30 application-specific minicourses taught by COMSOL specialists covering a wide array of disciplines
* Keynote talks from industry leaders and prominent researchers
* User-contributed paper and poster presentations
* The introduction of the newest simulation tools and technologies
* An exhibition showcasing products offered by COMSOL Partners
* The chance to interact with peers and explore the simulation work of fellow engineers

The Boston COMSOL Conference 2015 will be held October 7-9, 2015 at the Boston Marriott Newton, Newton, MA. For more details and to register to attend, visit: [www.comsol.com/conference2015/boston](http://www.comsol.com/conference2015/boston).

Explore the contributions to the 2014 COMSOL Conference at: [www.comsol.com/2014-user-presentations](http://www.comsol.com/2014-user-presentations)

**About COMSOL**

COMSOL provides simulation software for product design and research to technical enterprises, research labs, and universities through 22 offices and a distributor network throughout the world. Its flagship product, COMSOL Multiphysics®, is a software environment for modeling and simulating any physics-based system and for building applications. A particular strength is its ability to account for coupled or multiphysics phenomena. Add-on products expand the simulation platform for electrical, mechanical, fluid flow, and chemical applications. Interfacing tools enable the integration of COMSOL Multiphysics® simulation with all major technical computing and CAD tools on the CAE market.

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